Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.061”**

**ANODE**

**.042 X .42”**

**.061”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .042 x .042”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .061” X .061” DATE: 11/9/21**

**MFG: MICROSEMI THICKNESS .008” P/N: 1N4993B**

**DG 10.1.2**

#### Rev B, 7/1